



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICATION NO. : 10/725,933
APPLICANT : Yang et al.
FILED : December 3, 2003
FOR : FAN OUT TYPE WAFER LEVEL PACKAGE
STRUCTURE AND METHOD OF THE SAME
CONFIRMATION NO. : 4487
ART UNIT : 2891
EXAMINER : David A. Zarneke
ATTORNEY DOCKET NO. : HK9225US

February 26, 2008

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office Action dated October 29, 2007, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 7 of this paper.